DESCRIPTION

~~DOUBLE-SIDED POLISHING METHOD~~

TECHNICAL FIELD

[0001]

The present invention relates to a double-side polishing method of simultaneously polishing both surfaces of a wafer while a polishing agent is supplied.

BACKGROUND ART

[0002]

The shrinkage of semiconductor devices increases a need for highly flat semiconductor wafers used as their substrate with improved productivity. In such circumstances, double-side polishing has been used for polishing wafers instead of conventional single-side polishing because of higher precision.

Figure 8 shows a schematic diagram of a common double-side polishing apparatus of a planetary gear type. The double-side polishing apparatus 101 includes upper and lower turn tables. The upper turn table is movable upward and downward and can apply a load against a wafer interposed between the upper and lower turn tables by pressing the lower turn table. As shown in FIG. 8, the double-side polishing apparatus 101 includes a sun gear 107 disposed inside the lower turn table and an internal gear 108 disposed outside the lower turn table.

[0003]

A carrier 105 to hold the wafer is disposed between the upper and lower turn tables, and can rotate with its outer circumference engaged with the sun gear 107 and the internal gear 108. The carrier 105 is

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